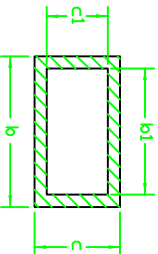


REV.	DESCRIPTION	DATE	APPROVED
01	REVISED PER DCN D20827	09/13/1993	Y.M.K.

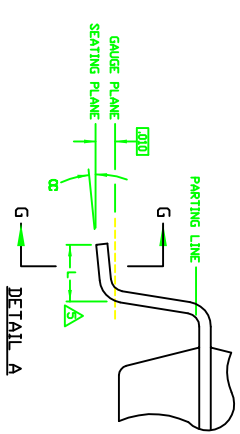
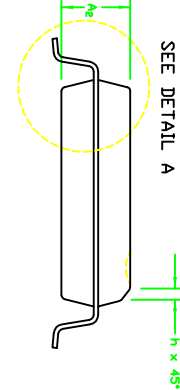
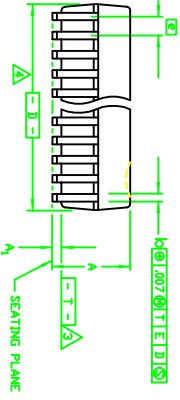
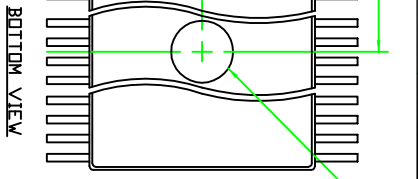
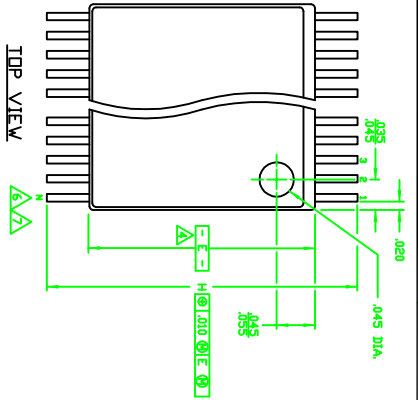


SECTION G-G A

SCALE: NONE

NOTES:

- △ MAXIMUM DIE THICKNESS ALLOWABLE IS .025.
- △ DIMENSIONING & TOLERANCING PER ANSI Y14.3M 1993.
- △ "A" IS A REFERENCE DATUM.
- △ "D" & "E" ARE REFERENCE DATUMS AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .006 INCHES PER SIDE.
- △ "L" IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
- △ "N" IS THE NUMBER OF TERMINAL POSITIONS.
- △ TERMINAL POSITIONS ARE SHOWN FOR REFERENCE ONLY.
- △ FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN .003 INCHES AT SEATING PLANE.
- △ CONTROLLING DIMENSION: INCHES.
- 10. COUNTRY OF ORIGIN LOCATION AND EJECTOR PIN ON PACKAGE BOTTOM IS OPTIONAL AND DEPENDS ON ASSEMBLY LOCATION.
- △ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 INCHES AND .010 INCHES FROM THE LEAD TIPS.
- 12. THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MO-11B, VARIATIONS AA, AB, EXCEPT CHAMFER DIMENSION h. JEDEC SPECIFICATION FOR h IS .015/.025".



REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
01	REVISED PER DCN D20827	09/13/1993	Y.M.K.

APPROVALS			
DESIGNED BY	DATE	APPROVED BY	DATE
S.DURHAM	07/19/1993		
C.DONOHUE	07/19/1993		
K.MURRAY	07/19/1993		
Y.M.K.	07/19/1993		

TITLE			
PACKAGE OUTLINE, .300 INCH, 48 & 56 LEAD, .025 INCH PITCH, S.S.D.P.			
REV.	DATE	BY	CHKD.
01	8/1/93	B	

SCALE 8/1		SHEET 1 OF 2	
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